

IN THE CLAIMS

Please cancel claim 1.

Please amend claims 4 as marked below.

Claim 1. (Canceled)

Claim 2. (Canceled)

Claim 3. (Canceled)

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Claim 4. (Currently Amended) A bump inspection method for inspecting shapes of a plurality of bumps on an inspection object each of said bumps having a planar top portion, said bumps being formed into a substantially hemispherical shape by reflowing of solder, ~~and said top portions of said bumps being shaped into a planar shape by a coining process~~, and said top portions of all of said bumps of said inspection object being on the same plane, comprising the steps of:

a shaping step of shaping said top portions of said bumps into a planar shape by coining such that said top portions of all of said bumps of said inspection object are on the same plane;

an illumination step of illuminating said top portions with a vertical parallel pencil of light thereto through a telecentric optical system;

an observation step of observing by a telecentric optical system having an optical axis in conformity with that of said illumination optical system;

another observation step of observing the images of said top portions within a predetermined range of said inspection object through said observation optical system;
and

a processing step of analyzing the shapes of said bumps on the basis of the
images of said top portions by said observation portion;

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said processing step including an analyzing stage of analyzing the areas of
said planar top portions for said individual bumps and a judging stage of judging whether or not
the areas of said top portions are within a predetermined range.

Claim 5. (Canceled)

Claim 6. (Canceled)
